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From: Charles A. Brill
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mezenner

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

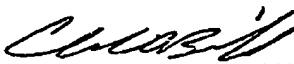
Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

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NAME OF INVENTOR(S):	
Mezenner	
TITLE OF INVENTION:	
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TI-33824	20-0668
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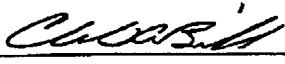
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AMENDMENT

11 April 2005

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

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 Charles A. Brill

 11 April 2005

Date

Dear Sir:

In response to the Examiner's Action mailed 10 January 2005, applicant amends as follows:

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